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Docket No.: MAS-FIN-207

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

By:  Date: May 8, 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.	: 10/700,087	Confirmation No: 2800
Applicant	: Juergen Hoegerl, et al.	
Filed	: Nov. 3, 2003	
Art Unit	: 3729	
Examiner	: Carl J. Arbes	
Title	: Method and Placement System for Populating a Substrate with Electronic Components	
Docket No.	: MAS-FIN-207	
Customer No.	: 24131	
Date of Notice of Allowance	:	

LETTER

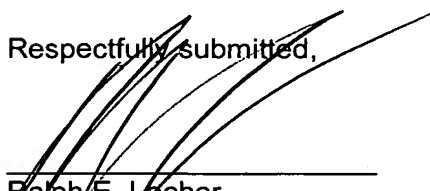
Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450

Sir:

Please note that the German Priority document number 101 21 578.9 dated May 3, 2001 was filed on February 11, 2004 in the U.S Patent Office. Please find enclosed copies of the following:

- 1) Claim for Priority
- 2) The cover page of priority document; and
- 3) The filing receipt of PTO.

Respectfully submitted,

  
\_\_\_\_\_  
Ralph E. Locher  
Reg. No. 41,947

Date: May 8, 2006  
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/sa



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By: Markus Nolff Date: February 11, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 10/700,087  
Applicant : Juergen Hoegerl, et al.  
Filed : November 3, 2003  
Title : Method and Placement System for Populating a Substrate with  
Electronic Components  
Docket No. : MAS-FIN-207  
Customer No. : 24131

**CLAIM FOR PRIORITY**

Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450

Sir:

Claim is hereby made for a right of priority under Title 35, U.S. Code, Section 119, based upon the German Patent Application 101 21 578.9, filed May 3, 2001.

A certified copy of the above-mentioned foreign patent application is being submitted herewith.

Respectfully submitted,

Markus Nolff  
For Applicant

Markus Nolff  
Reg. No. 37,006

Date: February 12, 2004

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/av

# BUNDESREPUBLIK DEUTSCHLAND



## Prioritätsbescheinigung über die Einreichung einer Patentanmeldung

BEST AVAILABLE COPY

**Aktenzeichen:** 101 21 578.9

**Anmeldetag:** 03. Mai 2001

**Anmelder/Inhaber:** Infineon Technologies AG, 81669 München/DE

**Bezeichnung:** Verfahren und Bestückungssystem zum Bestücken  
eines Substrats mit elektronischen Bauteilen

**IPC:** H 05 K, H 01 L, B 65 G

Die angehefteten Stücke sind eine richtige und genaue Wiedergabe der ursprünglichen Unterlagen dieser Patentanmeldung.

München, den 4. Februar 2004  
Deutsches Patent- und Markenamt  
Der Präsident  
Im Auftrag

Faust

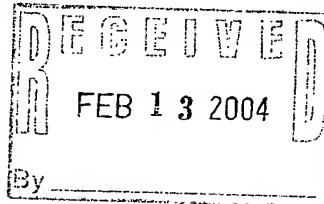


## UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/700,087	11/03/2003	3729	896	MAS-FIN-207	3	27	2

LERNER AND GREENBERG, P.A.  
POST OFFICE BOX 2480  
HOLLYWOOD, FL 33022-2480



CONFIRMATION NO. 2800  
FILING RECEIPT



\*OC000000011881891\*

Date Mailed: 02/11/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

**Applicant(s)**

Jurgen Hogerl, Regensburg, GERMANY;  
Jens Pohl, Bernhardswald, GERMANY;  
Uta Sasse, Feldkirchen-Westerham, GERMANY;  
Ingo Wennemuth, Munchen, GERMANY;

**Domestic Priority data as claimed by applicant**

This application is a CON of PCT/DE02/01523 04/25/2002

**Foreign Applications**

GERMANY 101 21 578.9 05/03/2001

**If Required, Foreign Filing License Granted:** 02/11/2004

**Projected Publication Date:** To Be Determined - pending completion of Missing Parts

**Non-Publication Request:** No

**Early Publication Request:** No

**Title**

Method and placement system for populating a substrate with electronic components